

Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info	Subsectionals *	A-D
	Manufacturing Info		* : Required Field

Supplier Information						
Company Name *	STMicroelectronics	Response Date *	2021-05-25			
Company Unique ID	NL 008751171B01					
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section			
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section			
Authorized Representative *	Floriana SAN BIAGIO	Representative Title	AMS Material Declaration champion			
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section			

Uncertainty Statement

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Legal Statement

Supplier Acceptance * true Legal Declaration * Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product					
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date	
	1DO7*0372AAW	Α	64BA	2021-05-25	
	Amount	UoM	Unit type	ST ECOPACK Grade	
	77	mg	Each	ECOPACK® 3	
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony				

Manufacturing information						
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles				
1	260	3				
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	life.augmented		
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	1	moradginomoa		

Package Designator	Package Size	Nbr of instances	Shape	
DSO	4.85 x 3.9	8	Gull wing	
Comment	O7 SO 08 .15 JEDEC; MDF is valid for TS372IDT			

QueryList: RoHS Directive 2011/65/EU-8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015						
	Response					
1 - Product(s) meets EU RoHS requirement w	- Product(s) meets EU RoHS requirement without any exemptions true					
2 - Product(s) meets EU RoHS requirements	2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)					
3 - Product(s) meets EU RoHS requirements	- Product(s) meets EU RoHS requirements by application of the selected exemption(s) FALSE					
4 - Product(s) does not meet EU RoHS requir	- Product(s) does not meet EU RoHS requirements and is not under exemptions false					
Exemption Id. Description						

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020					
Query Response					
- Product(s) meets EU ELV requirements without any exemptions true					
2 - Product(s) meets EU RoHS requirements	false				
Exemption Id.	semption Id. Description				

Query			Response	
L - The product does not contain identified substance from California Prop 65 List, no exposure to	consumers is foreseen		true	
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen				
Substance	ppm in product			
Vickel	0.00		0	
ead	0.00		0	
ead-Borate Glass	0			
ead Zirconate Titanate	0			
Antimony trioxide	0			
Bisphenol A	0.00		0	

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014					
Query	Response				
Product(s) requires marking for the p for Administration of the control of pollu	false				
2 - Product(s) is eligible for marking with	false				
Lead (Pb)	PBB & PBDE				
0	0				

QueryList: REACH-19th January 2021						
	Response					
1 - Product(s) does not contain REACH Substa	1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH					
CategoryLevel_Name	ategoryLevel_Name CategoryLevel_Threshold amount in product (mg) Application					
,						
2 - Product(s) does not contain REACH S within REACH	ubstances Of Very High Concern in any Embedded	article nor Homogeneous Material ab	ove the limits per the definition	true		
CategoryLevel_Name	Categoryl evel Threshold		Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material		
,			,			

QueryList: Responsible metals sourcing				
Query	Response			
The component is containing at least one of the following metals: Cobalt, Gold, Tantalum, Tin, Tungsten.	true			
The following metals are present is the component :	Tin,			
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .				

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update						
	Response					
The Product does contain at least one of	false					
				Application Purpose		

China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020								
Query	Response							
The product contains adhesives identified under GB 33372	true							
All the adhesive impacted complies with GB 33372	true							

Material Composition Declaration: note: Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	1D07*0372AAW		76.5010		5999998.0	1000012.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	1.865	mg	supplier	die	Silicon(Si)	7440-21-3		1.819	mg	975335	23778
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.007	mg	3753	92
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.005	mg	2681	65
				supplier	passivation	Silicon oxide	7631-86-9		0.034	mg	18231	444
Leadframe	M-004 Copper and its alloys	28.765	mg	supplier	alloy	Copper(Cu)	7440-50-8		27.987	mg	972953	365843
				supplier	alloy	Iron(Fe)	7439-89-6		0.658	mg	22875	8601
				supplier	alloy	Iron phosphide	1310-43-6		0.040	mg	1391	523
				supplier	alloy	Zinc(Zn)	7440-66-6		0.035	mg	1217	458
				supplier	metallization	Silver (Ag)	7440-22-4		0.045	mg	1564	588
Die attach	M-015 Other organic materials	0.402	mg	supplier	glue	Silver(Ag)	7440-22-4		0.354	mg	880597	4627
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.020	mg	49751	261
				supplier	glue	Isobornyl acrylate	5888-33-5		0.020	mg	49751	261
				supplier	glue	Methyl acrylate polymer	87320-05-6		0.008	mg	19900	105
Bonding wires	M-004 Copper and its alloys	0.044	mg	supplier	wire	Copper(Cu)	7440-50-8		0.044	mg	1000000	575
Encapsulation	M-015 Other organic materials	44.707	mg	supplier	mold compound	Silica vitreous	60676-86-0		32.010	mg	715995	418431
				supplier	mold compound	Silicon oxide	7631-86-9		6.706	mg	149999	87660
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		3.353	mg	74999	43830
				supplier	mold compound	Phenol resin	26834-02-6		2.235	mg	49992	29216
				supplier	mold compound	Carbon black	1333-86-4		0.224	mg	5010	2928
				supplier	mold compound	Bismuth compound	7440-69-9		0.179	mg	4004	2340
Connections coating	Solder	0.718	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.718	mg	1000000	9386